

N-Channel MOSFET

Lead Free Package and Finish

Applications:

- Adaptor
- Charger
- SMPS

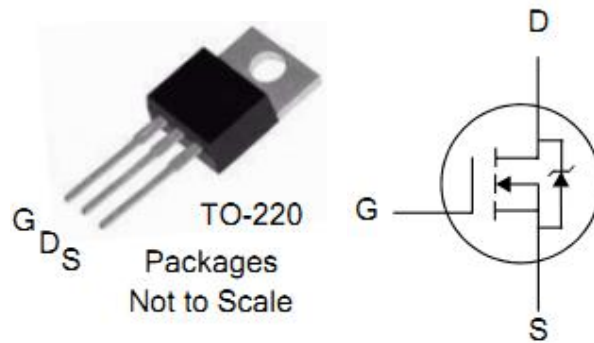
V_{DSS}	$R_{DS(ON)}$ (Typ.)	I_D (Silicon limited current)
60V	6.5m Ω	100A

Features:

- RoHS Compliant
- Low ON Resistance
- Low Gate Charge
- Peak Current vs Pulse Width Curve
- Inductive Switching Curves

Ordering Information

PART NUMBER	PACKAGE	BRAND
FTP08N06NE	TO-220	IPS



Absolute Maximum Ratings $T_C=25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	FTP08N06NE	Units
V_{DSS}	Drain-to-Source Voltage	60	V
I_D	Continuous Drain Current	100	A
	Continuous Drain Current $T_C = 100^\circ\text{C}$	60	A
I_{DM}	Pulsed Drain Current (NOTE *1)	400	A
V_{GS}	Gate-to-Source Voltage	± 20	V
E_{AS}	Single Pulse Avalanche Energy(NOTE *2)	347	mJ
T_L	Maximum Temperature for Soldering	300	$^\circ\text{C}$
T_J and T_{STG}	Operating Junction and Storage Temperature Range	150, -55 to 150	



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OFF Characteristics $T_C=25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
BV_{DSS}	Drain-to-Source Breakdown Voltage	60	--	--	V	$V_{GS}=0V, I_D=250\mu A$
I_{DSS}	Drain-to-Source Leakage Current	--	--	1	μA	$V_{DS}=60V, V_{GS}=0V$ $T_J=25^\circ\text{C}$
		--	--	500		$V_{DS}=48V, V_{GS}=0V$ $T_J=125^\circ\text{C}$
I_{GSS}	Gate-to-Source Forward Leakage	--	--	+100	nA	$V_{GS}=+20V$
	Gate-to-Source Reverse Leakage	--	--	-100		$V_{GS}= -20V$

ON Characteristics $T_J=25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
$R_{DS(ON)}$	Static Drain-to-Source On-Resistance	--	6.5	8.5	$m\Omega$	$V_{GS}=10V, I_D=40A$
$V_{GS(TH)}$	Gate Threshold Voltage	2	3	4	V	$V_{DS}=V_{GS}, I_D=250\mu A$
Pulse width $\leq 300\mu s$; duty cycle $\leq 2\%$						

Dynamic Characteristics Essentially independent of operating temperature

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
R_g	Gate Resistance	--	1.7	--	Ω	$f=1\text{MHz}, V_{GS}=0V,$ $V_{DS}=0V$
C_{iss}	Input Capacitance	--	3348	--	pF	$V_{GS}=0V, V_{DS}=25V$ $f=1.0\text{MHz}$
C_{oss}	Output Capacitance	--	349	--		
C_{rss}	Reverse Transfer Capacitance	--	300	--		
Q_g	Total Gate Charge	--	73	--	nC	$I_D=50A, V_{DD}=48V$ $V_{GS}=10V$
Q_{gs}	Gate-to-Source Charge	--	16	--		
Q_{gd}	Gate-to-Drain ("Miller") Charge	--	30	--		

Resistive Switching Characteristics Essentially independent of operating temperature

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
$t_{d(ON)}$	Turn-on Delay Time	--	25.4	--	ns	$V_{DD}=30V, I_D=50A,$ $V_G=10V R_G=6\Omega$
t_{rise}	Rise Time	--	18	--		
$t_{d(OFF)}$	Turn-Off Delay Time	--	60	--		
t_{fall}	Fall Time	--	22	--		



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Source-Drain Diode Characteristics $T_c=25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
I_S	Continuous Source Current (Body Diode)	--	--	100	A	$T_C=25^\circ\text{C}$
I_{SM}	Maximum Pulsed Current (Body Diode)	--	--	400	A	
V_{SD}	Diode Forward Voltage	--	--	1.2	V	$I_{SD}=30\text{A}$, $V_{GS}=0\text{V}$
t_{rr}	Reverse Recovery Time	--	36	--	ns	$I_F=20\text{A}$ $di/dt=100\text{A}/\mu\text{s}$
Q_{rr}	Reverse Recovery Charge	--	55	--	nC	
Pulse width $\leq 300\mu\text{s}$; duty cycle $\leq 2\%$						

Notes:

*1. Repetitive rating; pulse width limited by maximum junction temperature.

*2. $L=0.5\text{mH}$, $I_D=37\text{A}$, Start $T_J=25^\circ\text{C}$

Test Circuits and Waveforms

Figure 14. Gate Charge Test Circuit

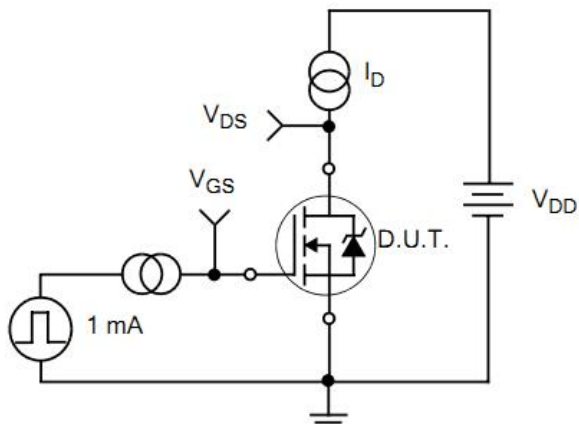


Figure 15. Gate Charge Waveforms

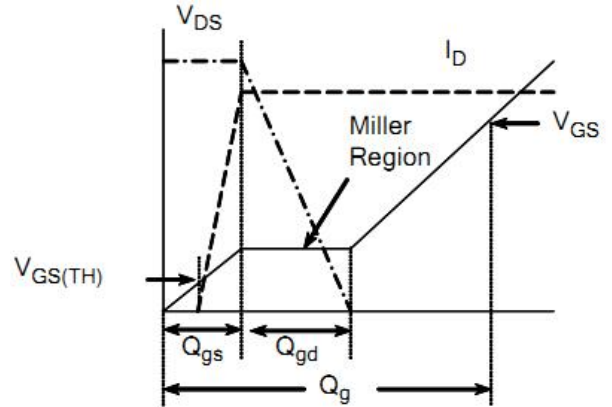


Figure 16. Resistive Switching Test Circuit

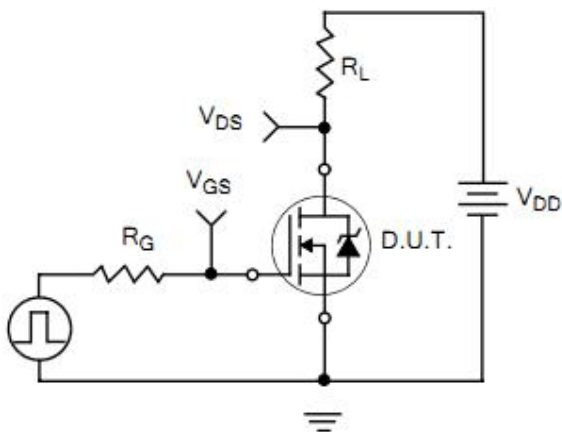


Figure 17. Resistive Switching Waveforms

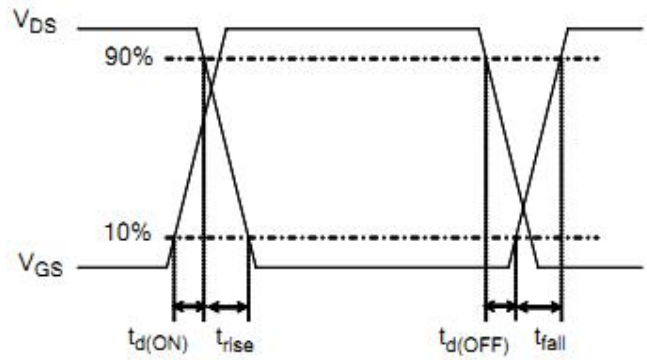


Figure 18. Diode Reverse Recovery Test Circuit

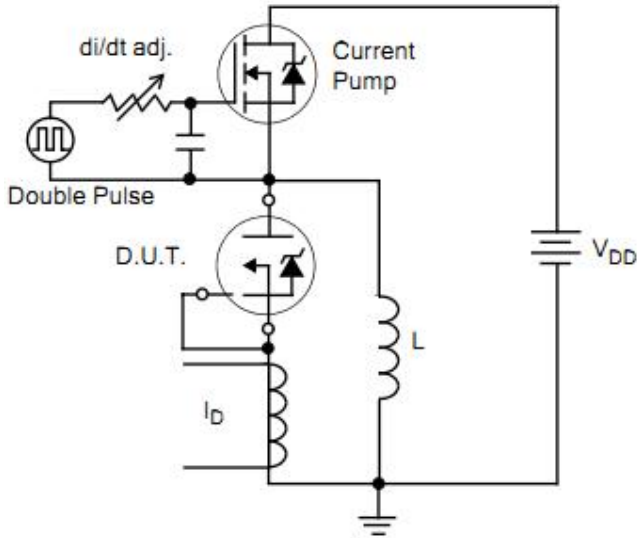


Figure 19. Diode Reverse Recovery Waveform

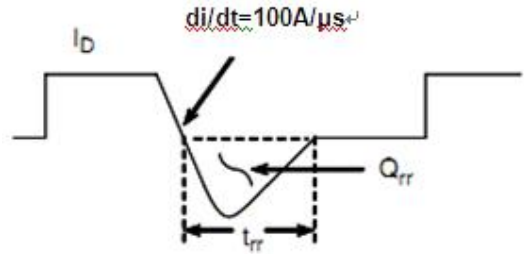


Figure20.Unclamped Inductive Switching Test Circuit

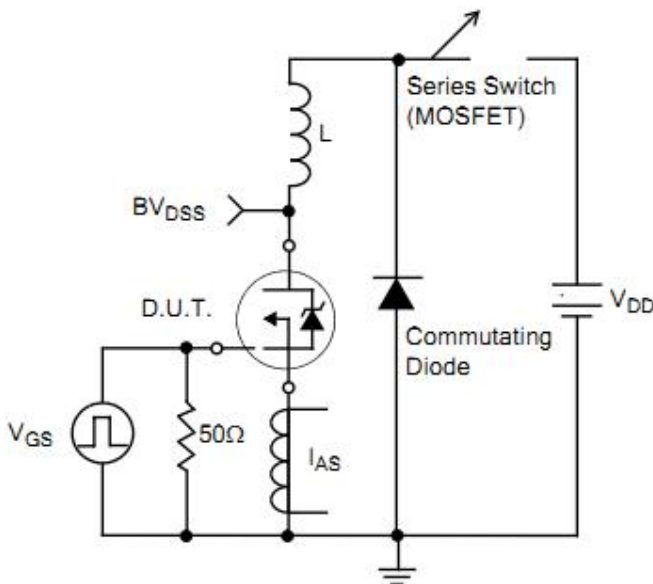
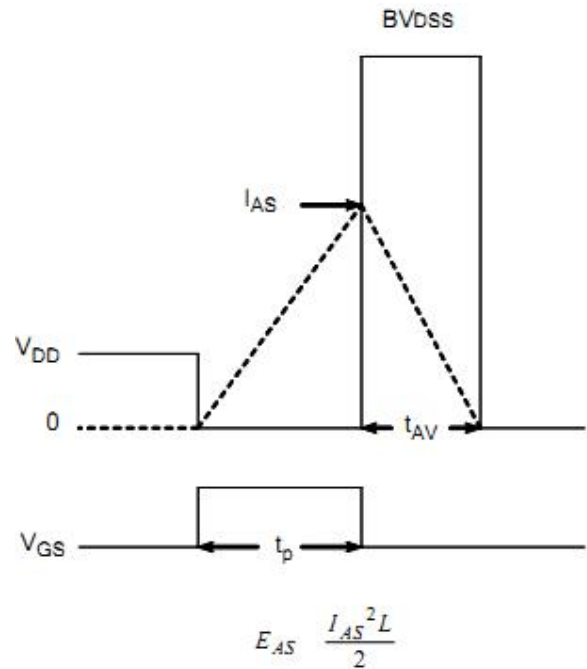


Figure21.Unclamped Inductive Switching Waveform





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